L Number	Hits	Search Text	DB	Time stamp
1	22	"5399232"	USPAT; US-PGPUB;	2003/10/08 09:48
2	2	("5399232").PN.	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/10/08 09:49
3	4	(("5578528") or ("20020158039")).PN.	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/10/08 09:49
-	22537	"MEMS"	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/12 12:57
-	5873	etching and recess and bonding	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/11
-	240	"MEMS" and (etching and recess and bonding)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/11 11:03
-	1576	microsensors	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/11
-	5488	sacrificial adj layer	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/11 11:04
-	914	"MEMS" and (sacrificial adj layer)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/11
-	69	microsensors and ("MEMS" and (sacrificial adj layer))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/11
-	2627	"MEMS" and mirror	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/12 10:35
-	611590	cavity	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/12 10:35
-	744	("MEMS" and mirror) and cavity	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/12
-	10978	substrate and sacrificial	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/12

Search History 10/8/03 9:52:35 AM

			· · · · · · · · · · · · · · · · · · ·	
_	175	(("MEMS" and mirror) and cavity) and	USPAT;	2003/04/12
	İ	(substrate and sacrificial)	US-PGPUB;	10:49
	İ		EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	10114	variable adj capacitor	USPAT;	2003/04/12
	}	,	US-PGPUB;	10:49
			EPO; JPO;	1 20.15
			DERWENT;	
			1	
_	224	"MEMC" and (wominh) and and others)	IBM_TDB	2002/04/12
	224	"MEMS" and (variable adj capacitor)	USPAT;	2003/04/12
			US-PGPUB;	10:50
			EPO; JPO;	
	Ì		DERWENT;	\ \ \ \ \
1			IBM_TDB	
-	0	("200100560618").PN.	USPAT;	2003/04/12
			US-PGPUB;	12:20
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
l –	2	("20010050618").PN.	USPAT;	2003/04/12
1		, 2332333337	US-PGPUB;	12:20
			,	12.20
1			EPO; JPO;	
]	1		DERWENT;	
			IBM_TDB	
-	7774	"shin-etsu"	USPAT;	2003/04/12
			US-PGPUB;	12:57
			EPO; JPO;	[
	1		DERWENT;	
			IBM TDB	
_	30719	wafer and hydrogen	USPAT;	2003/04/12
		,	US-PGPUB;	12:58
			EPO; JPO;	1 22.00
			DERWENT;	
1			IBM TDB	
_	631	"shin-etsu" and (wafer and hydrogen)		2003/04/12
-	631	shin-eusu and (water and hydrogen)	USPAT;	
			US-PGPUB;	12:58
			EPO; JPO;	
İ	1		DERWENT;	
[IBM_TDB	
-	1974	stacking adj faults	USPAT;	2003/04/12
	1		US-PGPUB;	12:58
1	1		EPO; JPO;	1
1			DERWENT;	
1	1		IBM TDB	
_	42	("shin-etsu" and (wafer and hydrogen))	USPAT;	2003/04/12
	1	and (stacking adj faults)	US-PGPUB;	13:10
	1		EPO; JPO;	• • •
j .			DERWENT;	
	Į į			
	2267641		IBM_TDB	2003/04/23
-	3267641	vacuum or pressure	USPAT;	2003/04/12
	1		US-PGPUB;	13:12
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	15	(("shin-etsu" and (wafer and hydrogen))	USPAT;	2003/04/12
	į.	and (stacking adj faults)) and (vacuum or	US-PGPUB;	13:12
		pressure)	EPO; JPO;	
		F =	DERWENT;	
			IBM TDB	
	1	L	TOP IDD	I